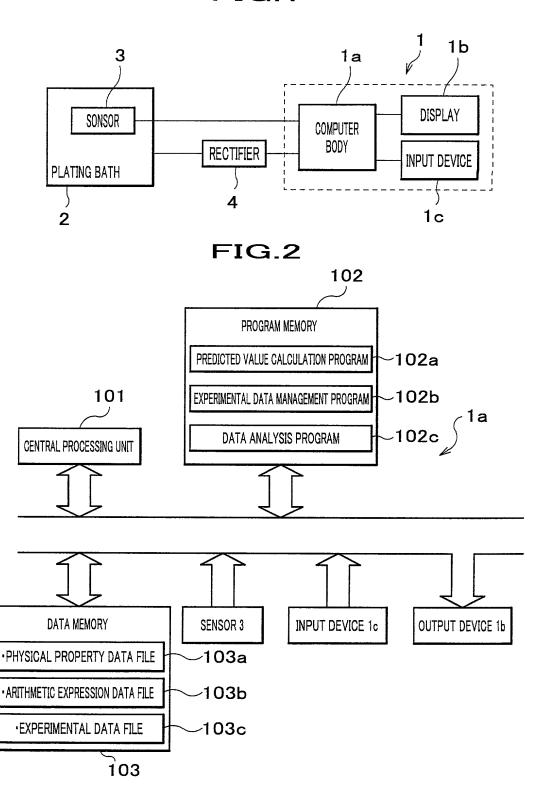
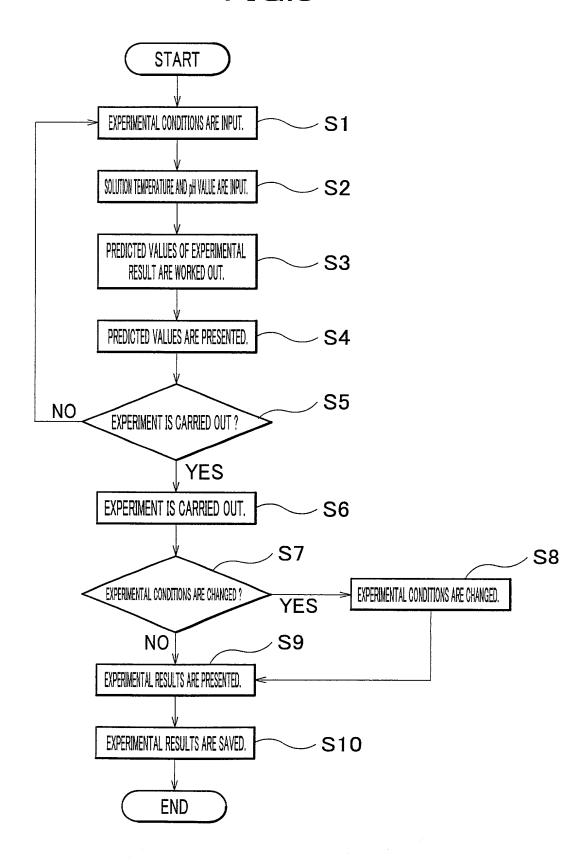
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FIG.1

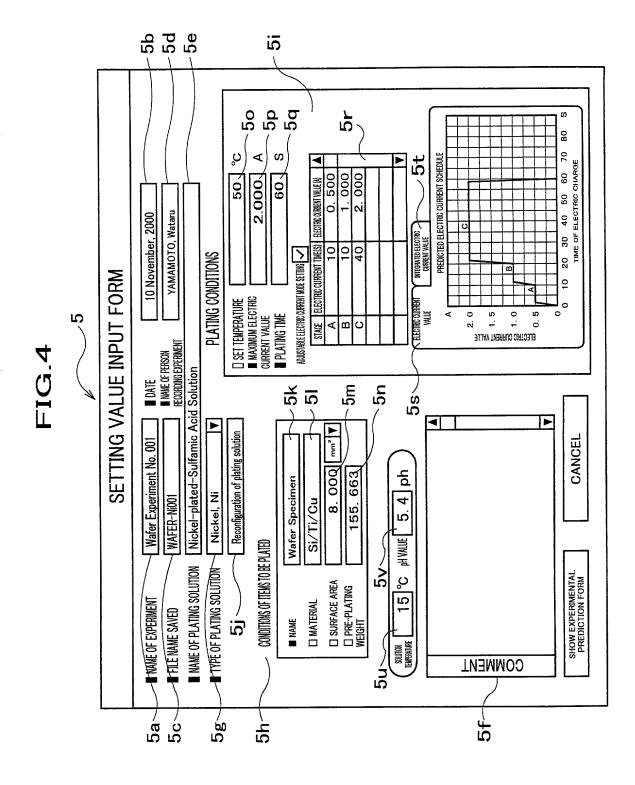


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FIG.3



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FIG.5A

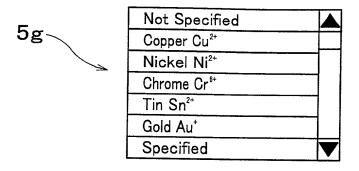


FIG.5B

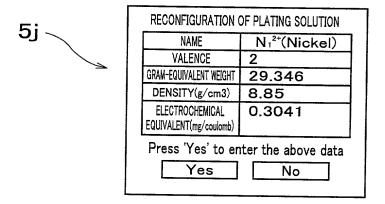
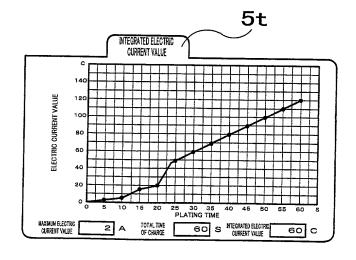
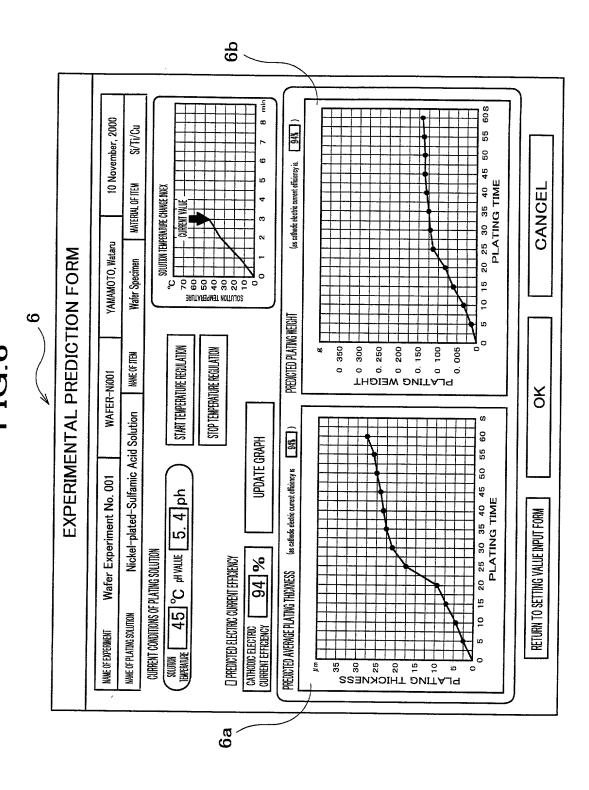


FIG.5C

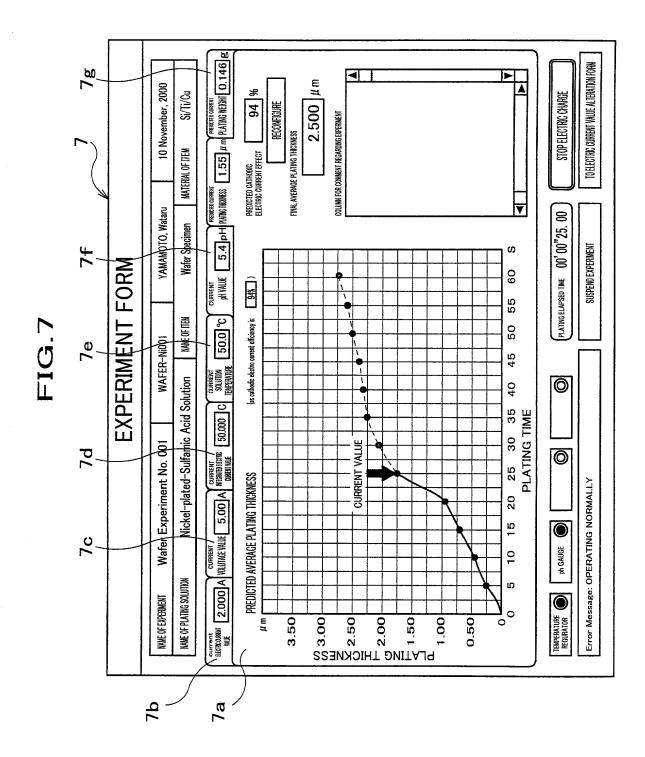


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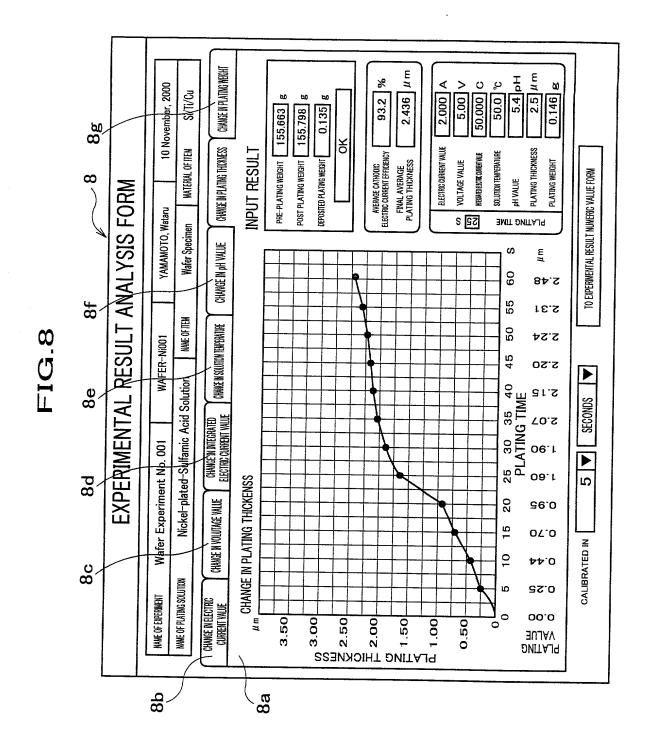


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-IG.9

10 November, 2000 Si/Ti/Cu **EXPERIMENTAL RESULT NUMERICAL VALUE FORM** NATERIAL OF ITEM YAMAMOTO, Wataru Wafer Specimen pH VALUE(pH) XXXX SAVE IN CSV FORMAT NAME OF THEM WAFER-Ni001 Nickel-plated-Sulfamic Acid Solution XXXX XXX MEGNIE BECITC CURFAT WLIEW Wafer Experiment No. 001 XXX VOLTAGE VALUE(A) ELECTRIC CURRENT VALUE(A) XXXX XXXX ×××× NAME OF PLATING SOLUTION 22 23 25 26 27 27 30 30 30 NAME OF EXPERIMENT PLATING TIME(S)

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